



SOD-123

Plastic, surface-mounted package; 2 terminals;
2.675 mm x 1.6 mm x 1.15 mm body

塑料表面贴装封装；2 引脚；

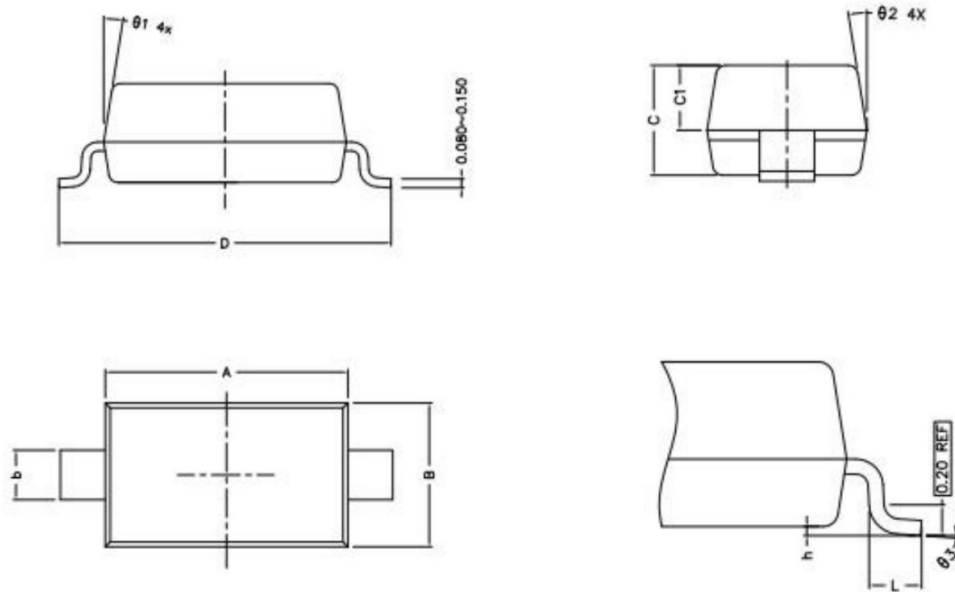
封装本体尺寸 2.675 mm x 1.6 mm x 1.15 mm

1. Mechanical Data 封装数据

Feature 特性	Description 描述
Package 封装	SOD-123
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Mounting Method Type 安装方式类型	Surface Mount Package 表面贴装封装
Material 材料	Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装，“绿色”成型复合材料；UL 可燃性等级 94V-0。
Dimensions 尺寸	2.675mm × 1.6mm × 1.15mm body 封装本体（不含引脚）尺寸为 2.675mm × 1.6mm × 1.15mm
Terminals Compliance 引脚合规	2 terminals, Tin Plated Leads, Solderable per MILSTD-202, Method 208 ^③ 2 个镀锡引脚，可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	0.01 grams (Approximate) 约 0.01 克

2. Package Outline Dimensions 封装外形尺寸

SOD-123



Symbol 符号	Millimeters 毫米	
	Min.最小值	Max.最大值
A	2.600	2.800
B	1.500	1.700
C	1.050	1.150
C1	0.600	0.700
D	3.550	3.850
L	0.250	0.450
b	0.450	0.650
h	0.020	0.120
$\theta 3$	0°	7°

3. Suggested Pad Layout 推荐焊盘布局

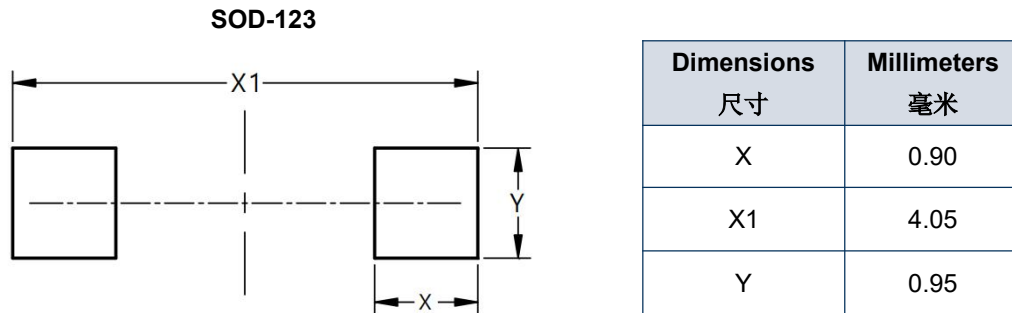


Fig. Soldering footprint for SOD-123

图 SOD-123 的引脚焊接

4. Minimum Packing Quantity 最小包装数量

Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
7	8	3000

Note:

Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

说明：上表所列包装数量仅为最低包装数量，并非最低订购数量。如需最低订购数量，请联系销售部门。



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For more information, please visit: www.jphl-semi.com

For business cooperation, please send an email to: sales@jphl-semi.com

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